EMTB85 Series



REGULATORY COMPLIANCE











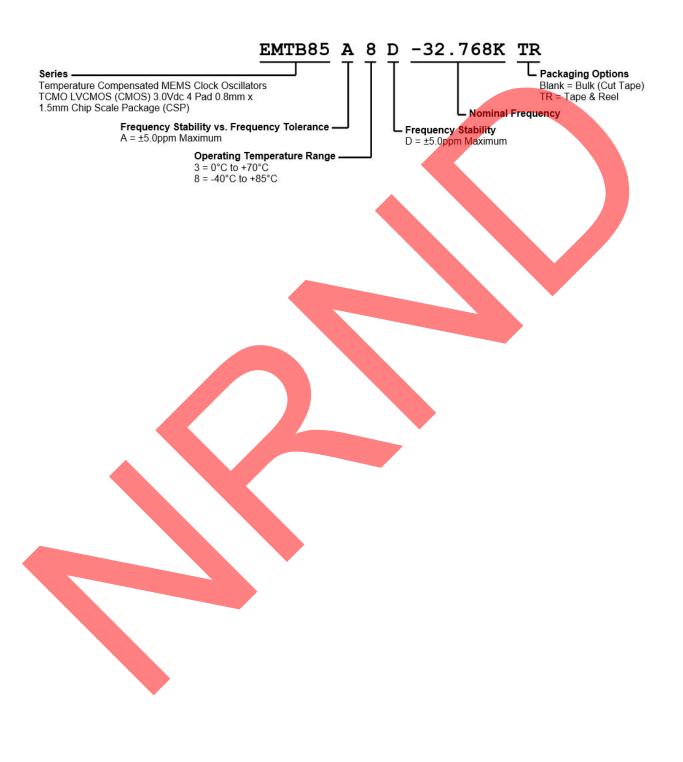
ITEM DESCRIPTION

Temperature Compensated MEMS Clock Oscillators TCMO LVCMOS (CMOS) 3.0Vdc 4 Pad 0.8mm x 1.5mm Chip Scale Package (CSP)

ELECTRICAL SPECIFICATIONS		
Nominal Frequency	32.768kHz	
Frequency Tolerance/Stability	Inclusive of Operating Temperature Range, Output Load <mark>Change (±</mark> 20%), and Reflow, at Vdd= <mark>3.0Vd</mark> c ±5.0ppm Maximum	
Frequency Stability vs. Frequency	Measured at 25°C ±2°C, at Vdd=3.0Vdc, Post Reflow	
Tolerance	±5.0ppm Maximum	
Frequency Stability vs. Input Voltage	±0.75ppm Maximum (±10%)	
Frequency Stability vs. Aging	±1ppm/Year Maximum (at 25°C)	
Operating Temperature Range	0°C to +70°C	
	-40°C to +85°C	
Supply Voltage	3.0Vdc ±10%	
Core Operating Current	0.99μA Typical (at 25°C), 1.52 <mark>μA Maximum</mark>	
Output Stage Operating Current	0.065μA/Vpp Typical, 0.125μA/Vp <mark>p Maxim</mark> um	
Input Current	No Load, Nominal Vdd	
	1.2µA Typical (at 25°C), 1.9µA Maximum	
Output Voltage Logic High (V _{он})	IOH = -10μA	
	90% of V <mark>dd Mini</mark> mum	
Output Voltage Logic Low (V _{OL})	$IOL = +10\mu$ A	
D: (F. 11.7)	10% of Vdd Maximum	
Rise/Fall Time	Measured at 10% to 90% of waveform	
Duty Cycle	100nSec Typical, 200nSec Maximum Measured at 50% of waveform	
Duty Cycle	50 ±2(%)	
Load Drive Capability	15pF Maximum	
Output Logic Type	CMOS	
Peak to Peak Jitter (tPK)	2.5µSec Maximum	
Period Jitter (RMS)	Measured at 25°C	
	33nSec Typical	
Power Supply Ramp	Measured at 0Vdc to 90% of Vdd	
	100mSec-Maximum	
Start Up Time	Measured at Nominal Vdd	
	180mSec Typical, 380mSec Maximum at Operating Temperature Range of -40°C to +85°C 180mSec Typical, 350mSec Maximum at Operating Temperature Range of 0°C to +70°C	
Storage Temperature Range	-55°C to +125°C	
Storage remperature Kange	-0.0 C t0 +12.0 C	

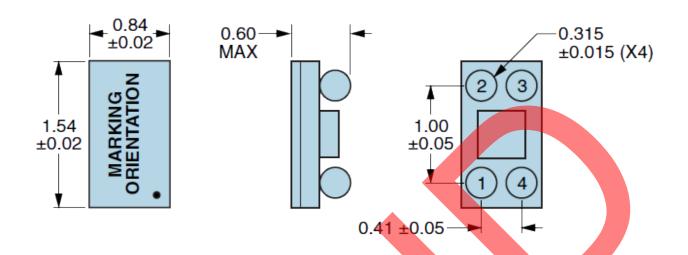


PART NUMBERING GUIDE

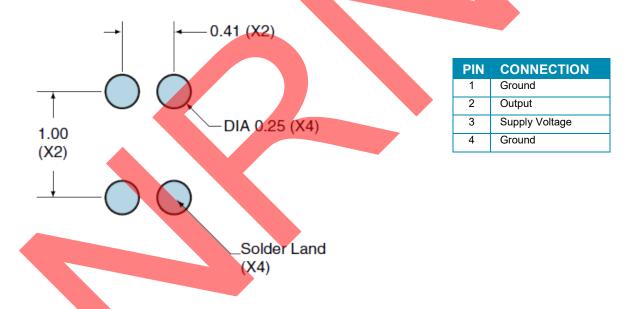




MECHANICAL DIMENSIONS



SUGGESTED SOLDER PAD LAYOUT



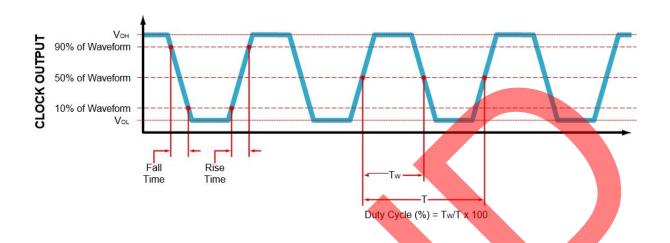
All Tolerances are ±0.1

All Dimensions in Millimeters

EMTB85 Series

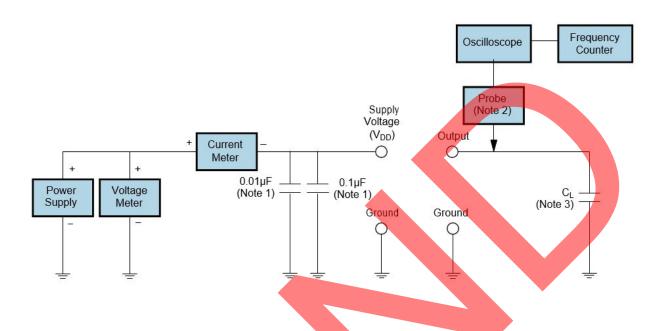


OUTPUT WAVEFORM





TEST CIRCUIT FOR CMOS OUTPUT



- Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less Than 2mm) to the package ground and supply voltage pin is required.

 Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz)
- Passive probe is recommended.
- Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

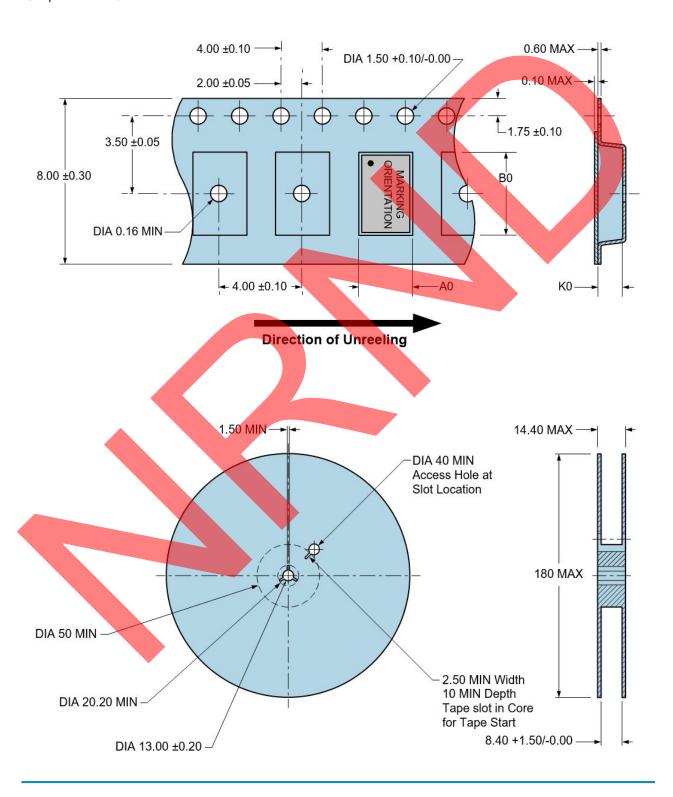
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TAPE & REEL DIMENSIONS

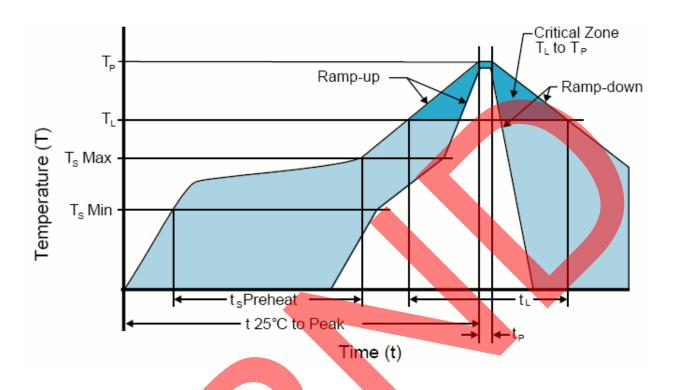
Quantity per Reel: 3,000 Units

All Dimensions in Millimeters
Compliant to EIA-481





RECOMMENDED SOLDER REFLOW METHOD



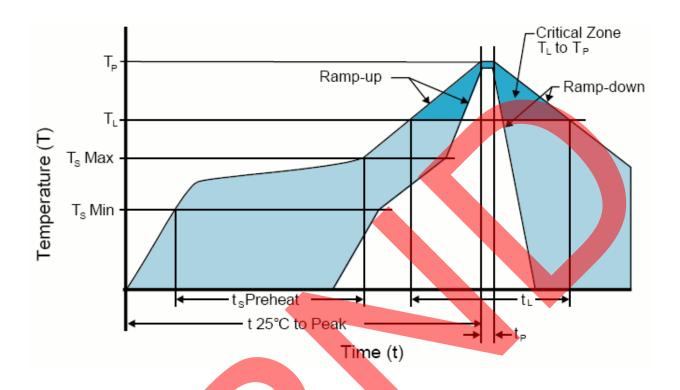
HIGH TEMPERATURE INFRARED/CONVECTION		
T _s MAX to T _∟ (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T _s MIN)	150°C	
- Temperature Typical (T _s TYP)	175°C	
- Temperature Maximum(T _s MAX)	200°C	
- Time (t _s MIN)	60 - 180 Seconds	
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	217°C	
- Time (t _L)	60 - 150 Seconds	
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(Tp Target)	250°C +0/-5°C	
Time within 5°C of actual peak (tp)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED	/CONVECTION
T _s MAX to T _L (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum(T _s MAX)	N/A
- Time (t _s MIN)	60 - 120 Seconds
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T _P)	240°C Maximum
Target Peak Temperature(TP Target)	240°C Maximum 2 Times/230°C Maximum 1Time
Time within 5°C of actual peak (t₂)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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